

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc2636hde-hmx10#pbf

(Engineering Calculation)

DFN 4mm X 3mm Exposed Pad

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TOTAL MASS (g) : 0.03174

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001752 | 1000000 | 55198.8867188 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.013123 | 975000 | 413456.03125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000323 | 24000 | 10176.5068359 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000004 | 300 | 126.024856567 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000009 | 700 | 283.555908203 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.013459 | 1000000 | 424042.09375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000626 | 1000000 | 19715.6035156 | | |
| | | External Plating Total: | | | | 0.000626 | 1000000 | 19715.6035156 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000302 | 1000000 | 9514.87695312 | | |
| Internal Plating Total: | | | | 0.000302 | 1000000 | 9514.87695312 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000836 | 750000 | 26339.1953125 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000279 | 250000 | 8790.23339844 | | |
| Die Attach Total: | | | | 0.001115 | 1000000 | 35129.4296875 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.001876 | 130000 | 59105.6523438 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.012410 | 860000 | 390992.09375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000144 | 10000 | 4536.89453125 | | |
| | | Encapsulation Total: | | | | 0.014430 | 1000000 | 454634.65625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000056 | 1000000 | 1764.34802246 | | |
| | | | | | TOTAL MASS (g) : | 0.03174 | | |